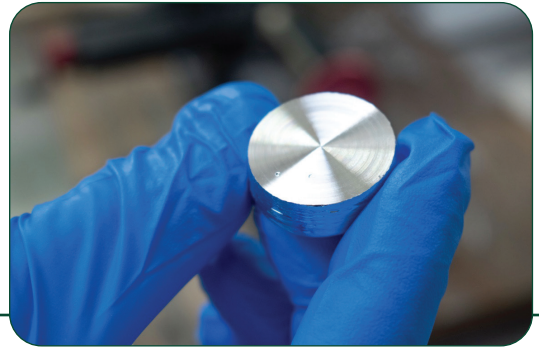


APPLICATION NOTE

Solder Pot Analysis



Reasons to Have the Solder Pot Analyzed

During the wave, dip, and selective soldering processes, it is known that the solder pot can become contaminated as the metals involved dissolve into the wave. As these impurities increase within the solder pot, wetting performance can be affected, leading to defects such as bridging and non-wetting.

Aside from contaminants being leached from the printed circuit board, solder analysis can also be used to ensure that the solder pot contains the proper composition to ensure optimal soldering.

Indium Corporation Solder Analysis Service

Most solder pots, especially those consistently used on a regular basis, will require periodic maintenance of the alloy within.

Solder pot analysis is important for maintaining solder joint quality and optimal first-pass soldering yield. By allowing a solder pot to collect too high a level of contaminants from circuit boards and components, the solder can get sluggish, causing overly large fillets, poor wetting, bridging, and expensive rework and repair. Indium Corporation's solder analysis service allows customers to purchase an individual analysis or pre-paid solder analysis mailers in bulk.

Requesting Solder Pot Analysis

Different options:

- Request a solder analysis mailer by placing a purchase order.
- Submit a blanket order for a number of samples or for a period of time. The customer will send the samples with identifying information for processing.

Indium Corporation asks that at least 100grams of the material be sent for analysis.

Upon receiving the sample, Indium Corporation will analyze the sample to determine the existence of a number of elements including gold, silver, copper, cadmium, and indium, among others. The estimated time to complete a solder pot analysis is 24 hours.

Provided With Every Solder Bar Order

Indium Corporation provides a free Certificate of Conformance containing the lot number and product specifications, and a free Certificate of Analysis displaying the exact composition of that material, with every purchase of bar and wire solder.

Technical Support

Indium Corporation's internationally experienced engineers provide in-depth technical assistance to our customers. Thoroughly knowledgeable in all facets of Materials Science as it applies to the electronics and semiconductor sectors, Technical Support Engineers provide expert advice in solder properties, alloy compatibility and selection of solder preforms, wire, ribbon, and paste. Indium Corporation's Technical Support Engineers provide rapid response to all technical inquiries.

This product data sheet is provided for general information only. It is not intended, and shall not be construed, to warrant or guarantee the performance of the products described which are sold subject exclusively to written warranties and limitations thereon included in product packaging and invoices. All Indium Corporation's products and solutions are designed to be commercially available unless specifically stated otherwise.

All of Indium Corporation's solder paste and preform manufacturing facilities are IATF 16949:2016 certified. Indium Corporation is an ISO 9001:2015 registered company.

From One Engineer To Another®

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